



Data sheet acquired from Harris Semiconductor SCHS047D

August 1998 - Revised March 2000

CMOS Analog Multiplexers/Demultiplexers with Logic Level Conversion

The CD4051B, CD4052B, and CD4053B analog multiplexers are digitally-controlled analog switches having low ON impedance and very low OFF leakage current. Control of analog signals up to $20V_{P-P}$ can be achieved by digital signal amplitudes of 4.5V to 20V (if $V_{DD}-V_{SS} = 3V$, a $V_{DD}-V_{EE}$ of up to 13V can be controlled; for $V_{DD}-V_{EE}$ level differences above 13V, a $V_{DD}-V_{SS}$ of at least 4.5V is required). For example, if $V_{DD} = +4.5V$, $V_{SS} = 0V$, and $V_{EE} = -13.5V$, analog signals from -13.5V to +4.5V can be controlled by digital inputs of 0V to 5V. These multiplexer circuits dissipate extremely low quiescent power over the full $V_{DD}-V_{SS}$ and $V_{DD}-V_{EE}$ supply-voltage ranges, independent of the logic state of the control signals. When a logic "1" is present at the inhibit input terminal, all channels are off.

The CD4051B is a single 8-Channel multiplexer having three binary control inputs, A, B, and C, and an inhibit input. The three binary signals select 1 of 8 channels to be turned on, and connect one of the 8 inputs to the output.

The CD4052B is a differential 4-Channel multiplexer having two binary control inputs, A and B, and an inhibit input. The two binary input signals select 1 of 4 pairs of channels to be turned on and connect the analog inputs to the outputs.

The CD4053B is a triple 2-Channel multiplexer having three separate digital control inputs, A, B, and C, and an inhibit input. Each control input selects one of a pair of channels which are connected in a single-pole, double-throw configuration.

When these devices are used as demultiplexers, the "CHANNEL IN/OUT" terminals are the outputs and the "COMMON OUT/IN" terminals are the inputs.

Features

- · Wide Range of Digital and Analog Signal Levels
- Digital 3V to 20V
- Analog...... ≤20V_{P-P}
- Low ON Resistance, 125 Ω (Typ) Over 15VP-P Signal Input Range for VDD-VEE = 18V
- High OFF Resistance, Channel Leakage of ± 100 pA (Typ) at V_{DD}-V_{EE} = 18V
- Logic-Level Conversion for Digital Addressing Signals of 3V to $20V (V_{DD}-V_{SS} = 3V$ to 20V) to Switch Analog Signals to $20V_{P-P} (V_{DD}-V_{EE} = 20V)$
- Matched Switch Characteristics, r_{ON} = 5 Ω (Typ) for $V_{DD}\text{-}V_{EE}$ = 15V
- Very Low Quiescent Power Dissipation Under All Digital-Control Input and Supply Conditions, $0.2\mu W$ (Typ) at $V_{DD}-V_{SS} = V_{DD}-V_{EE} = 10V$
- Binary Address Decoding on Chip
- 5V, 10V and 15V Parametric Ratings
- 10% Tested for Quiescent Current at 20V
- Maximum Input Current of $1\mu A$ at 18V Over Full Package Temperature Range, 100nA at 18V and 25^oC
- Break-Before-Make Switching Eliminates Channel
 Overlap

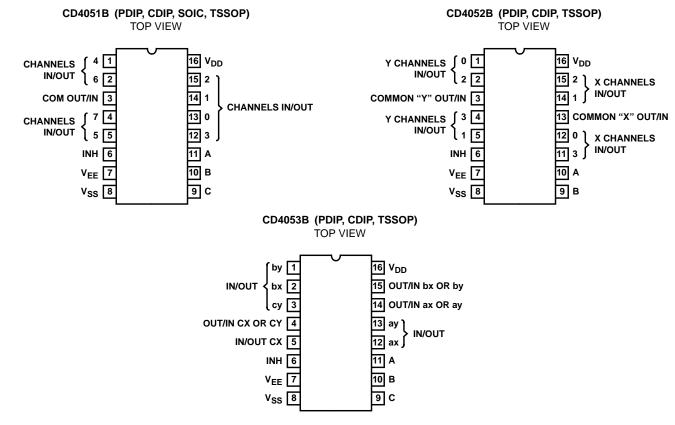
Applications

- Analog and Digital Multiplexing and Demultiplexing
- A/D and D/A Conversion
- Signal Gating

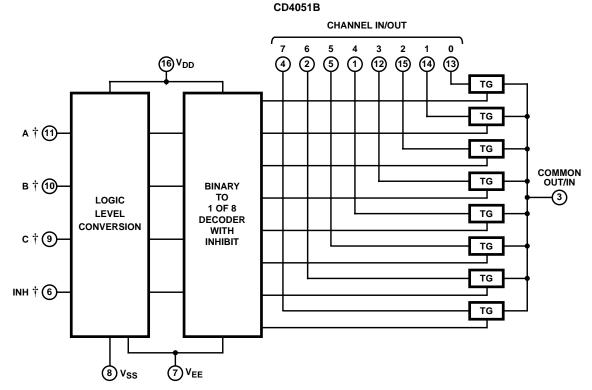
Ordering Information

PART NUMBER	TEMP. RANGE (^o C)	PACKAGE
CD4051BF, CD4052BF, CD4053BF	-55 to 125	16 Ld CERAMIC DIP
CD4051BE, CD4052BE, CD4053BE	-55 to 125	16 Ld PDIP
CD4051BM, CD4051BNS	-55 to 125	16 Ld SOIC
CD4051BPW, CD4052BPW, CD4053BPW	-55 to 125	16 Ld TSSOP



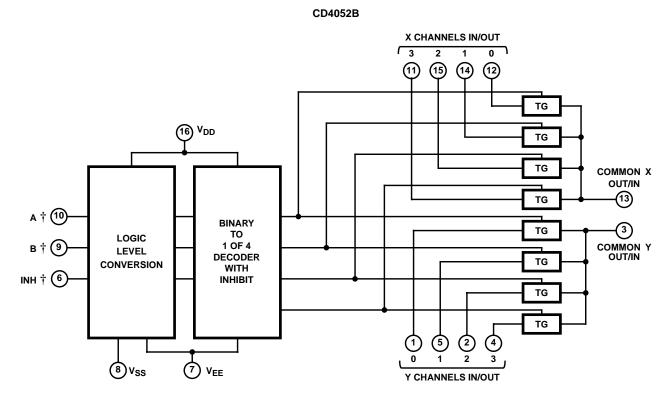


Functional Block Diagrams

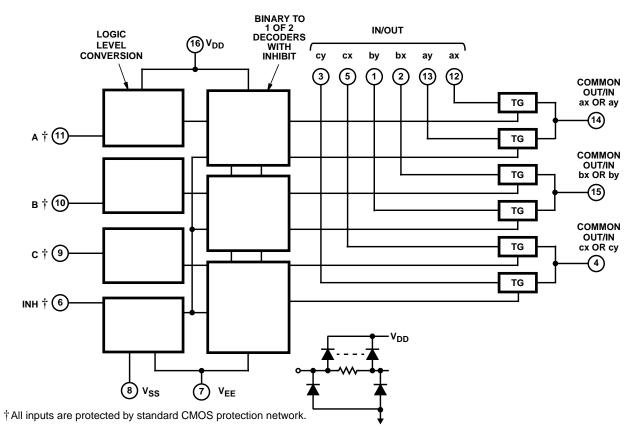


†All inputs are protected by standard CMOS protection network.

Functional Block Diagrams (Continued)



CD4053B



I	NPUT S					
INHIBIT	С	В	Α	"ON" CHANNEL(S)		
CD4051B						
0	0	0	0	0		
0	0	0	1	1		
0	0	1	0	2		
0	0	1	1	3		
0	1	0	0	4		
0	1	0	1	5		
0	1	1	0	6		
0	1	1	1	7		
1	Х	X X X		None		
CD4052B						
INHIBIT		В	Α			
0		0	0	Ox, Oy		
0		0	1	1x, 1y		
0		1	0	2x, 2y		
0	1		1	3х, Зу		
1		Х		None		
CD4053B						
INHIBIT	A	OR B OR	C			
0	0 0			ax or bx or cx		
0		1		ay or by or cy		
1		Х		None		

TRUTH TABLES

X = Don't Care

Absolute Maximum Ratings

Absolute Maximum Ratings	Thermal Information		
Supply Voltage (V+ to V-)	Thermal Resistance (Typical, Note 1)	θ _{JA} (^o C/W)	θ _{JC} (^o C/W)
Voltages Referenced to V _{SS} Terminal0.5V to 20V	E Package	67	N/A
DC Input Voltage Range	F Package	115	45
DC Input Current, Any One Input	D Package	73	N/A
	NS Package	64	N/A
Operating Conditions	PW Package	108	N/A
	Maximum Junction Temperature (Ceramic F	Package)	175 ⁰ C
Temperature Range	Maximum Junction Temperature (Plastic F	Package)	150 ⁰ C
	Maximum Storage Temperature Range	6	5 ^o C to 150 ^o C
	Maximum Lead Temperature (Soldering 1	0s)	265 ⁰ C

(SOIC - Lead Tips Only)

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. The package thermal impedance is calculated in accordance with JESD51.

Electrical Specifications Common Conditions Here: If Whole Table is For the Full Temp. Range, $V_{SUPPLY} = \pm 5V$, $A_V = +1$, $R_L = 100\Omega$, Unless Otherwise Specified (Note 3)

		CONDIT	IONS		LIMITS AT INDICATED TEMPERATURES (^o C)								
									25			1	
PARAMETER	V _{IS} (V)	V _{EE} (V)	V _{SS} (V)	V _{DD} (V)	-55	-40	85	125	MIN	TYP	MAX	UNITS	
SIGNAL INPUTS (VIS) A	ND OUTPUT	S (V _{OS})	•										
Quiescent Device	-	-	-	5	5	5	150	150	-	0.04	5	μA	
Current, I _{DD} Max	-	-	-	10	10	10	300	300	-	0.04	10	μA	
	-	-	-	15	20	20	600	600	-	0.04	20	μA	
	-	-	-	20	100	100	3000	3000	-	0.08	100	μA	
Drain to Source ON	-	0	0	5	800	850	1200	1300	-	470	1050	Ω	
Resistance r_{ON} Max $0 \le V_{IS} \le V_{DD}$	-	0	0	10	310	330	520	550	-	180	400	Ω	
	-	0	0	15	200	210	300	320	-	125	240	Ω	
Change in ON	-	0	0	5	-	-	-	-	-	15	-	Ω	
Resistance (Between Any Two Channels),	-	0	0	10	-	-	-	-	-	10	-	Ω	
Δr_{ON}	-	0	0	15	-	-	-	-	-	5	-	Ω	
OFF Channel Leakage Current: Any Channel OFF (Max) or ALL Channels OFF (Common OUT/IN) (Max)	-	0	0	18	±100 (Note 2)	±1000 ((Note 2)	-	±0.01	±100 (Note 2)	nA	
Capacitance: Input, C _{IS}	-	-5	5-	5	-	-	-	-	-	5	-	pF	
Output, C _{OS} CD4051					-	-	-	-	-	30	-	pF	
CD4052					-	-	-	-	-	18	-	pF	
CD4053					-	-	-	-	-	9	-	pF	
Feedthrough C _{IOS}					-	-	-	-	-	0.2	-	pF	
Propagation Delay Time	V _{DD}	R _L = 200		5	-	-	-	-	-	30	60	ns	
(Signal Input to Output	л	$C_{L} = 50p$ $t_{r}, t_{f} = 20$		10	-	-	-	-	-	15	30	ns	
		r, q – 20		15	-	-	-	-	-	10	20	ns	

CD4051B, CD4052B, CD4053B

	CONDITIONS					LIMITS AT INDICATED TEMPERATURES (^o C)							
PARAMETER									25			-	
	V _{IS} (V)	V _{EE} (V)	V _{SS} (V)	V _{DD} (V)	-55	-40	85	125	MIN	ТҮР	MAX	UNITS	
CONTROL (ADDRESS	or inhibit),	V _C					1			-		-	
Input Low Voltage, V _{IL} ,	$V_{IL} = V_{DD}$	$V_{EE} = V_{SS}$,		5	1.5	1.5	1.5	1.5	-	-	1.5	V	
Max	through 1kΩ;	R _L = 1kΩ I _{IS} < 2μΑ	2 to V _{SS} , on All	10	3	3	3	3	-	-	3	V	
	$V_{IH} = V_{DD}$	OFF Cha		15	4	4	4	4	-	-	4	V	
Input High Voltage, VIH,	 through 1kΩ 			5	3.5	3.5	3.5	3.5	3.5	-	-	V	
Min				10	7	7	7	7	7	-	-	V	
				15	11	11	11	11	11	-	-	V	
Input Current, I _{IN} (Max)	V _{IN} = 0, 18			18	±0.1	±0.1	±1	±1	-	±10 ⁻⁵	±0.1	μA	
Propagation Delay Time:													
Address-to-Signal OUT (Channels ON or OFF) See Figures 10, 11, 14	$t_{r}, t_{f} = 20ns,$ $C_{L} = 50pF,$ $R_{L} = 10k\Omega$	0	0	5	-	-	-	-	-	450	720	ns	
		0	0	10	-	-	-	-	-	160	320	ns	
		0	0	15	-	-	-	-	-	120	240	ns	
		-5	0	5	-	-	-	-	-	225	450	ns	
Propagation Delay Time:													
Inhibit-to-Signal OUT	$t_r, t_f = 20$ ns,	0	0	5	-	-	-	-	-	400	720	ns	
(Channel Turning ON) See Figure 11	$C_L = 50 pF,$ $R_L = 1 k\Omega$	0	0	10	-	-	-	-	-	160	320	ns	
Jan		0	0	15	-	-	-	-	-	120	240	ns	
		-10	0	5	-	-	-	-	-	200	400	ns	
Propagation Delay Time:													
Inhibit-to-Signal OUT (Channel Turning OFF) See Figure 15	$t_r, t_f = 20$ ns,	0	0	5	-	-	-	-	-	200	450	ns	
	$C_L = 50 pF,$ $R_I = 10 k\Omega$	0	0	10	-	-	-	-	-	90	210	ns	
, <u>-</u>	-	0	0	15	-	-	-	-	-	70	160	ns	
		-10	0	5	-	-	-	-	-	130	300	ns	
Input Capacitance, C _{IN} (Any Address or Inhibit Input)		·			-	-	-	-	-	5	7.5	pF	

NOTE:

2. Determined by minimum feasible leakage measurement for automatic testing.

Electrical Specifications

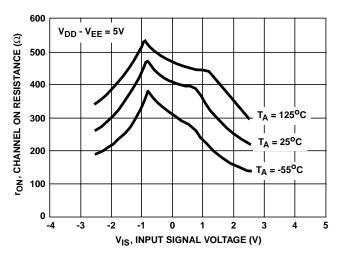
			LIMITS				
PARAMETER	V _{IS} (V)	V _{DD} (V)	R _L (kΩ)			ТҮР	UNITS
Cutoff (-3dB) Frequency Chan-	5 (Note 3)	10	1	V _{OS} at Common OUT/IN	CD4053	30	MHz
nel ON (Sine Wave Input)	$V_{EE} = V_{SS},$				CD4052	25	MHz
	201 c	$\log \frac{V_{OS}}{V_{IS}} = -3$	dB		CD4051	20	MHz
	2020	⁹ V _{IS}		V _{OS} at Any Channel		60	MHz

Electrical Specifications

		LIMITS						
PARAMETER	V _{IS} (V)	V _{DD} (V)	R _L (kΩ)				ТҮР	UNITS
Total Harmonic Distortion, THD	2 (Note 3)	5	10				0.3	%
-	3 (Note 3)	10					0.2	%
-	5 (Note 3)	15					0.12	%
	$V_{EE} = V_{SS}$	f _{IS} = 1kHz S	Sine Wave					%
40dB Feedthrough Frequency	5 (Note 3)	10	1	V _{OS} at Common OUT	ſ/IN	CD4053	8	MHz
All Channels OFF)	$V_{EE} = V_{SS},$		1			CD4052	10	MHz
	$20Log \frac{V_{OS}}{V_{IS}} = -40dB$				CD4051	12	MHz	
				V _{OS} at Any Channel	8	MHz		
-40dB Signal Crosstalk	5 (Note 3)	10	1	Between Any 2 Chan	3	MHz		
Frequency	$V_{EE} = V_{SS},$			Between Sections,	Measured or	n Common	6	MHz
	$20Log\frac{V_{OS}}{V_{IS}}=-40dB$			CD4052 Only	Measured or nel	Measured on Any Chan- nel		MHz
				Between Any Two	In Pin 2, Out Pin 14		2.5	MHz
				Sections, CD4053 Only	In Pin 15, Out Pin 14		6	MHz
Address-or-Inhibit-to-Signal Crosstalk	-	10	10 (Note 4)		-		65	mV _{PEAK}
	$V_{EE} = 0, V_{SS}$	_S = 0, t _r , t _f = S (Square W					65	mV _{PEAK}

4. Both ends of channel.

Typical Performance Curves





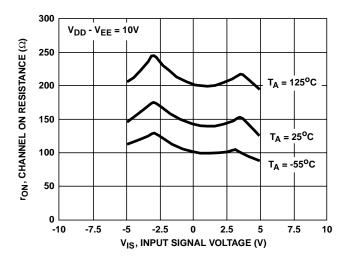
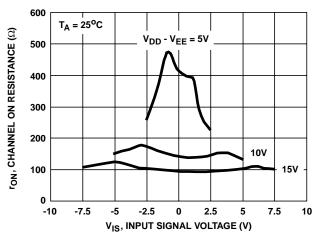


FIGURE 2. CHANNEL ON RESISTANCE vs INPUT SIGNAL VOLTAGE (ALL TYPES)

Typical Performance Curves (Continued)





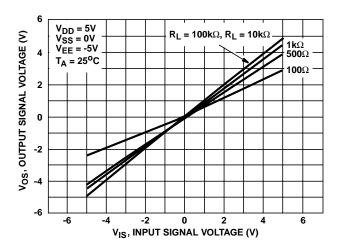


FIGURE 5. ON CHARACTERISTICS FOR 1 OF 8 CHANNELS (CD4051B)

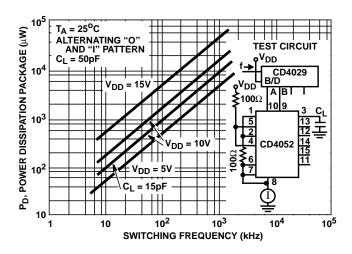


FIGURE 7. DYNAMIC POWER DISSIPATION vs SWITCHING FREQUENCY (CD4052B)

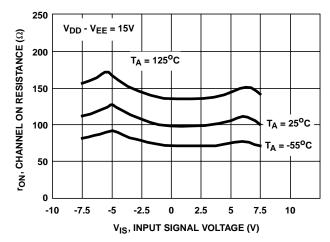


FIGURE 4. CHANNEL ON RESISTANCE vs INPUT SIGNAL VOLTAGE (ALL TYPES)

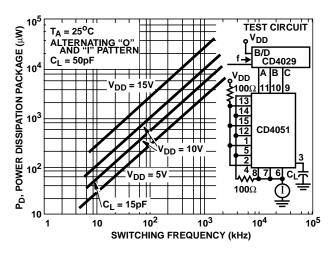


FIGURE 6. DYNAMIC POWER DISSIPATION vs SWITCHING FREQUENCY (CD4051B)

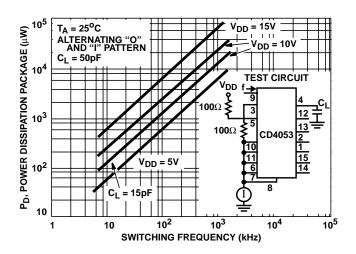
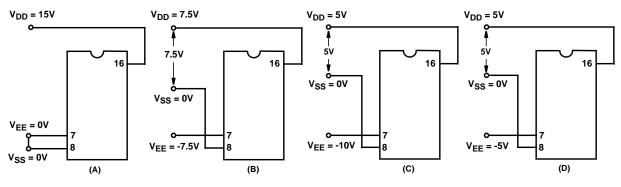


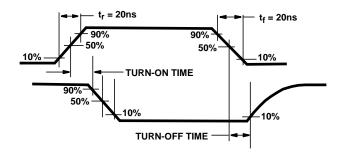
FIGURE 8. DYNAMIC POWER DISSIPATION vs SWITCHING FREQUENCY (CD4053B)

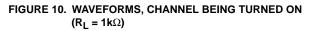
Test Circuits and Waveforms



NOTE: The ADDRESS (digital-control inputs) and INHIBIT logic levels are: "0" = V_{SS} and "1" = V_{DD}. The analog signal (through the TG) may swing from V_{EE} to V_{DD}.







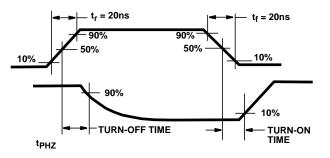


FIGURE 11. WAVEFORMS, CHANNEL BEING TURNED OFF $(R_L = 1k\Omega)$

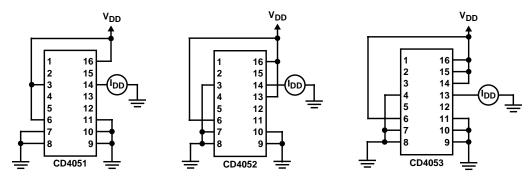
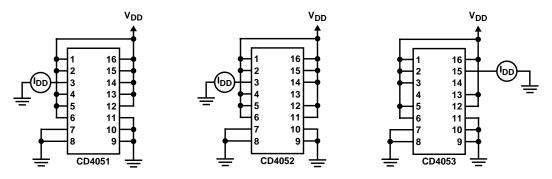
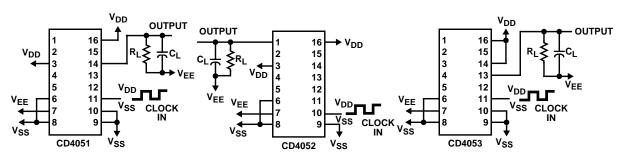


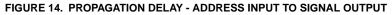
FIGURE 12. OFF CHANNEL LEAKAGE CURRENT - ANY CHANNEL OFF

Test Circuits and Waveforms (Continued)









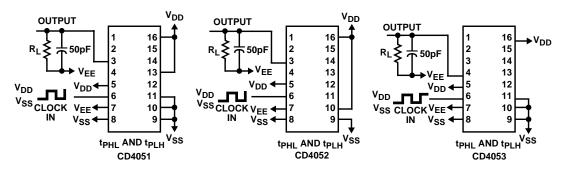
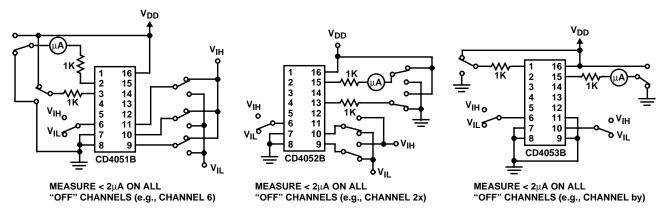


FIGURE 15. PROPAGATION DELAY - INHIBIT INPUT TO SIGNAL OUTPUT





Test Circuits and Waveforms (Continued)

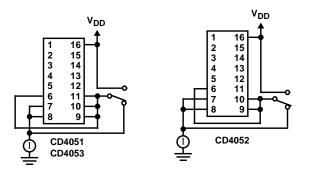
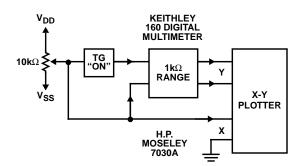


FIGURE 17. QUIESCENT DEVICE CURRENT





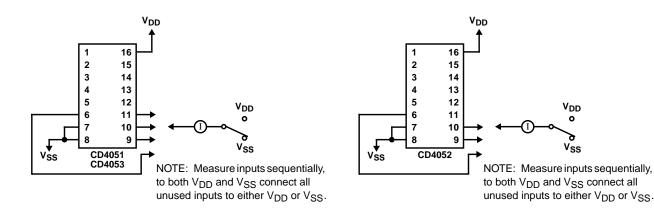


FIGURE 19. INPUT CURRENT

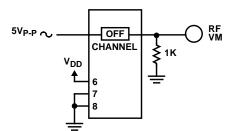
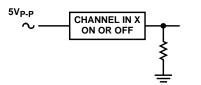
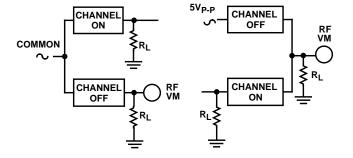


FIGURE 20. FEEDTHROUGH (ALL TYPES)







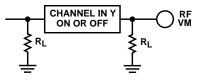


FIGURE 22. CROSSTALK BETWEEN DUALS OR TRIPLETS (CD4052B, CD4053B)

Test Circuits and Waveforms (Continued)

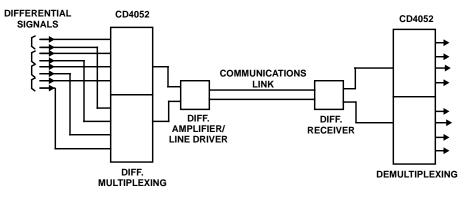


FIGURE 23. TYPICAL TIME-DIVISION APPLICATION OF THE CD4052B

Special Considerations

In applications where separate power sources are used to drive V_{DD} and the signal inputs, the V_{DD} current capability should exceed V_{DD}/R_L (R_L = effective external load). This provision avoids permanent current flow or clamp action on the V_{DD} supply when power is applied or removed from the CD4051B, CD4052B or CD4053B.

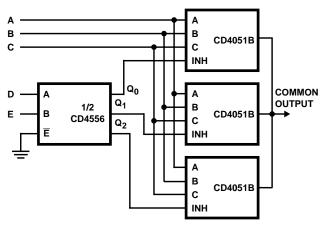


FIGURE 24. 24-TO-1 MUX ADDRESSING

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